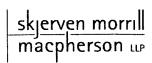
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Docket No.: M-12589 US

February 22, 2002

BOX PATENT APPLICATION Commissioner for Patents Washington, D.C. 20231

Inventor:

Enclosed herewith for filing is a patent application, as follows:

Hua Ji

HDP CVD Process For Void-Free Gap Fill Of A High Aspect Ratio Trench Title:

Return Receipt Postcard This Transmittal Letter (in duplicate) page(s) Specification (not including claims)

page(s) Claims page Abstract Sheet(s) of Drawings

page(s) Declaration For Patent Application and Power of Attorney

page(s) Recordation Form Cover Sheet (in duplicate)

page(s) Assignment

CLAIMS AS FILED

<u>For</u> Total Claims	Number <u>Filed</u> 29	-20	=	Number <u>Extra</u> 9	x	<u>Rate</u> \$18.00	==	\$ \$	Basic Fee 740.00 162.00
Independent Claims	2	-3	=	0	х	\$84.00	=	\$	0.00
Fee of for the first filing of one or more multiple dependent claims per application								\$	
Fee for Request for Extension of Time								\$	
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Respectfully submitted,

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Alan H. MacPherson Attorney for Applicant

Reg. No. 24,423

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